

Welcome to E-XFL.COM

Understanding <u>Embedded - DSP (Digital</u> <u>Signal Processors)</u>

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of <u>Embedded - DSP (Digital</u> <u>Signal Processors)</u>

Details

E·XFI

Product Status	Active
Туре	SC140 Core
Interface	Ethernet, I ² C, TDM, UART
Clock Rate	300MHz
Non-Volatile Memory	External
On-Chip RAM	448kB
Voltage - I/O	3.30V
Voltage - Core	1.10V
Operating Temperature	-40°C ~ 105°C
Mounting Type	Surface Mount
Package / Case	431-BFBGA, FCBGA
Supplier Device Package	431-FCPBGA (20x20)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=msc8112tvt2400v

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



N

Table of Contents

1	Pin A	Pin Assignments	
	1.1	FC-PBGA Ball Layout Diagrams4	
	1.2	Signal List By Ball Location7	
2	Electi	rical Characteristics	
	2.1	Maximum Ratings	
	2.2	Recommended Operating Conditions	
	2.3	Thermal Characteristics14	
	2.4	DC Electrical Characteristics14	
	2.5	AC Timings	
3	Hard	ware Design Considerations	
	3.1	Start-up Sequencing Recommendations	
	3.2	Power Supply Design Considerations	
	3.3	Connectivity Guidelines	
	3.4	External SDRAM Selection	
	3.5	Thermal Considerations	
4	Order	ng Information	
5	Packa	age Information	
6	Produ	act Documentation42	
7	Revis	ion History	

List of Figures

Figure 1.	MSC8112 Block Diagram
Figure 2.	StarCore [®] SC140 DSP Extended Core Block Diagram . 3
Figure 3.	MSC8112 Package, Top View 5
Figure 4.	MSC8112 Package, Bottom View 6
Figure 5.	Overshoot/Undershoot Voltage for V_{IH} and $V_{\text{IL}}, \ldots, 15$
Figure 6.	Start-Up Sequence: V_{DD} and V_{DDH} Raised Together 16
Figure 7.	Start-Up Sequence: V _{DD} Raised Before V _{DDH} with CLKIN
	Started with V _{DDH} 17
Figure 8.	Power-Up Sequence for V_{DDH} and V_{DD}/V_{CCSYN} 17
Figure 9.	Timing Diagram for a Reset Configuration Write 21

Figure 10 Internel Tick Specing for Memory Controller Signals 21
Figure To.Internal Tick Spacing for Memory Controller Signals 21
Figure 11. SIU Timing Diagram
Figure 12.CLKOUT and CLKIN Signals
Figure 13.DMA Signals
Figure 14.Asynchronous Single- and Dual-Strobe Modes Read
Timing Diagram
Figure 15.Asynchronous Single- and Dual-Strobe Modes Write
Timing Diagram
Figure 16.Asynchronous Broadcast Write Timing Diagram
Figure 17.DSI Synchronous Mode Signals Timing Diagram 29
Figure 18 TDM Inputs Signals 30
Figure 19 TDM Output Signals 30
Figure 20 UART Input Timing 31
Figure 21 UART Output Timing 31
Figure 22 Timer Timing 31
Figure 23 MDIO Timing Relationship to MDC 32
Figure 24 MII Mode Signal Timing 32
Figure 25 RMII Mode Signal Timing
Figure 26 SMII Mode Signal Timing
Figure 27 CPIO Timing 24
Figure 28 EE Din Timing
Figure 28.EE Pin Timing
Figure 29. Test Clock Input Timing Diagram
Figure 30.Boundary Scan (JTAG) Timing Diagram
Figure 31.Test Access Port Timing Diagram
Figure 32.TRST Timing Diagram
Figure 33.Core Power Supply Decoupling
Figure 34.V _{CCSYN} Bypass
Figure 35.MSC8112 Mechanical Information, 431-pin FC-PBGA
Package



Figure 3. MSC8112 Package, Top View

MSC8112 Dual Core Digital Signal Processor Data Sheet, Rev. 1

Electrical Characteristics

2.5 AC Timings

The following sections include illustrations and tables of **Icidia** grams, signals, and parallel I/O outputs and inputs. When systems such as DSP farms are developed using the DSI, use a device loading of 4 pF per pin. AC timings are based on a 20 pF load, except where noted otherwise, and a **50** mission line. For loads smaller than 20 pF, subtract 0.06 ns per pF down to 10 pF load. For loads larger than 20 pF, add 0.06 ns for SIU/Ethernet/DSI delay and 0.07 ns for GPIO/TDM/timer delay. When calculating overall loading, also consider additional RC delay.

2.5.1 Output Buffer Impedances

2.5.2 Start-Up Timing

Starting the device requires coordination among several input sequences including clocking, reset, a8eqtiome2.5.3 describes the clocking characteristi8ection 2.5.4describes the reset and power-up characteristics. You must use the following guidelines when starting up an MSC8112 device:

- PORESET and TRST must be asserted externally for the duration of the power-up sequen debeet for timing.
- If possible, bring up the DD and VDDH



Figure 11. SIU Timing Diagram

Figure 14 shows DSI asynchronous read signals timing.



Figure 14. Asynchronous Single- and Dual-Strobe Modes Read Timing Diagram



